



N-Channel 30-V (D-S) MOSFET

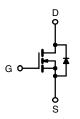
PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)		
30	0.0036 at V _{GS} = 10 V	25	58		
	0.0045 at V _{GS} = 4.5 V	23	36		

FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- Optimized for "Low Side" Synchronous Rectifier Operation
- New Low Thermal Resistance PowerPAK[®] Package with Low 1.07 mm Profile
- 100 % R_g Tested

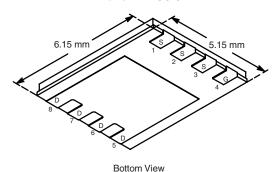


- DC/DC Converters
- Synchronous Rectifiers



N-Channel MOSFET

PowerPAK SO-8



Ordering Information: Si7894ADP-T1-E3 (Lead (Pb)-free)

Si7894ADP-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise n	oted		
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V_{DS}	30		V
Gate-Source Voltage		V_{GS}	± 12		
Continuous Dunin Comment /T 150 °C\a	T _A = 25 °C	- I _D	25	17	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		19	13	
Pulsed Drain Current (10 μs Pulse Width)		I _{DM}	60		Α
Continuous Source Current (Diode Conduction) ^a		I _S	4.5	1.6	
Avalanche Current	L = 0.1 mH	I _{AS}	45		
Manifestor Bassas Bissis attack	T _A = 25 °C	P _D	5.4	1.9	W
Maximum Power Dissipation ^a	T _A = 70 °C		3.4	1.2	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C
Soldering Recommendations (Peak Temperature)b, c				260	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	t ≤ 10 s	- R _{thJA}	18	23	°C/W	
Maximum Junction-to-Ambient*	Steady State		50	65		
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.0	1.5		

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. See Solder Profile (<u>www.vishay.com/ppg?73257</u>). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

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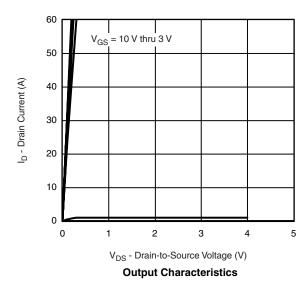
SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit	
Static							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.6		1.5	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	laco	V _{DS} = 30 V, V _{GS} = 0 V			1		
Zero Gate Voltage Diain Guirent	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
D : 0	D	$V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}$		0.0028	0.0036	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 23 \text{ A}$		0.0035	0.0045		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 25 A		110		S	
Diode Forward Voltage ^a	V_{SD}	I _S = 2.9 A, V _{GS} = 0 V		0.70	1.1	V	
Dynamic ^b				•			
Input Capacitance	C _{iss}			7330			
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{SS} = 0 \text{ V}, f = 1 \text{ MHz}$		910		pF	
Reverse Transfer Capacitance	C _{rss}			490			
Total Gate Charge	Q_g			58	85		
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 25 \text{ A}$		11.5		nC	
Gate-Drain Charge	Q_{gd}			11.5			
Gate Resistance	R_{g}		0.5	1.0	1.5	Ω	
Turn-On Delay Time	t _{d(on)}			22	35		
Rise Time	t _r	V_{DD} = 15 V, R_L = 15 Ω		15	25		
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong\text{1 A},~\text{V}_\text{GEN}=\text{10 V},~\text{R}_g=\text{6}~\Omega$		190	290	ns	
Fall Time	t _f			45	65		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 2.9 A, dI/dt = 100 A/μs		50	80		

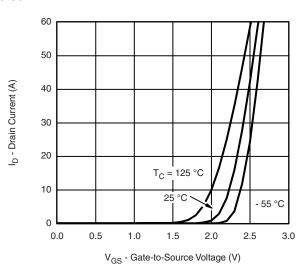
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





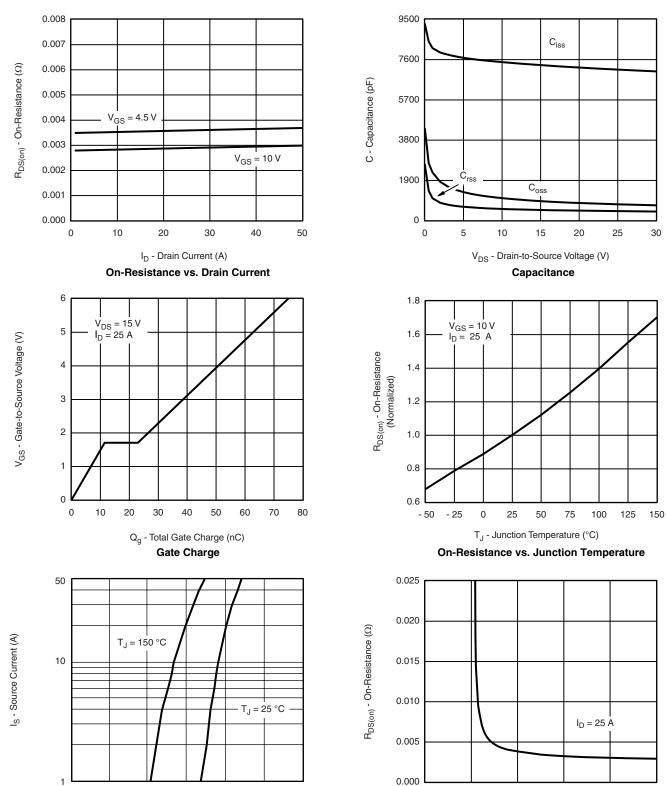
Transfer Characteristics







TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



0

4

V_{GS} - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage

0.0

0.2

0.4

0.6

 ${\sf V}_{\sf SD}$ - Source-to-Drain Voltage (V) **Source-Drain Diode Forward Voltage**

0.8

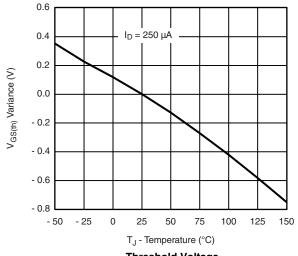
1.0

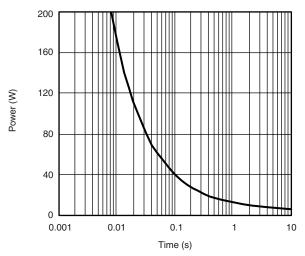
1.2

10

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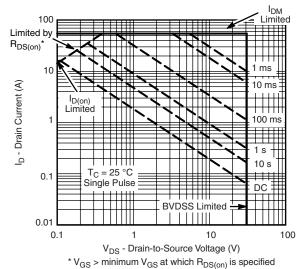
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



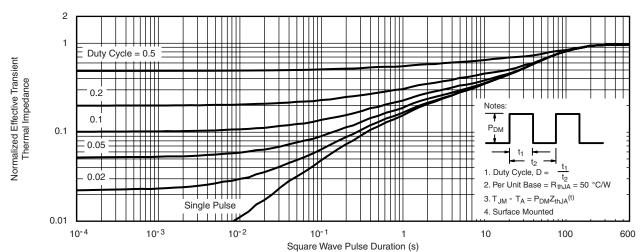


Threshold Voltage

Single Pulse Power



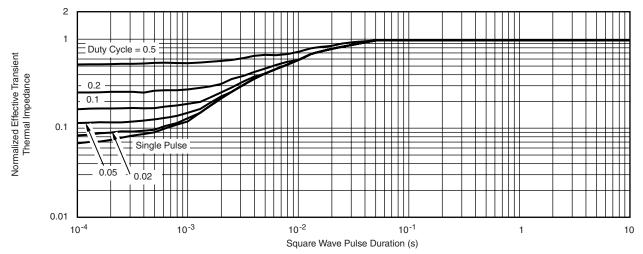
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Techology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?73167.



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